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(12) **United States Design Patent** (10) **Patent No.:** **US D902,057 S**  
**Elrod et al.** (45) **Date of Patent:** **\*\* Nov. 17, 2020**

- (54) **THERMAL IMAGING SENSOR**
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- (73) Assignee: **Fluke Electronics Corporation**,  
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- (\*\*) Term: **15 Years**
- (21) Appl. No.: **29/694,614**
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**Related U.S. Application Data**

- (62) Division of application No. 29/595,984, filed on Mar. 3, 2017, now Pat. No. Des. 854,430.
- (51) **LOC (12) Cl.** ..... **10-04**
- (52) **U.S. Cl.**  
USPC ..... **D10/52; D16/203**
- (58) **Field of Classification Search**  
USPC ..... D10/47, 52, 70, 30-32, 38, 40, 41, 46,  
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D10/114.6, 123, 125, 126, 128, 131;  
D11/1-4, 93, 94; D14/138, 144, 341,  
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CPC .. H04N 5/33; G01J 5/0846; G01J 2005/0077;  
G01J 2005/0081  
See application file for complete search history.

(57) **CLAIM**

The ornamental design for a thermal imaging sensor, as shown and described.

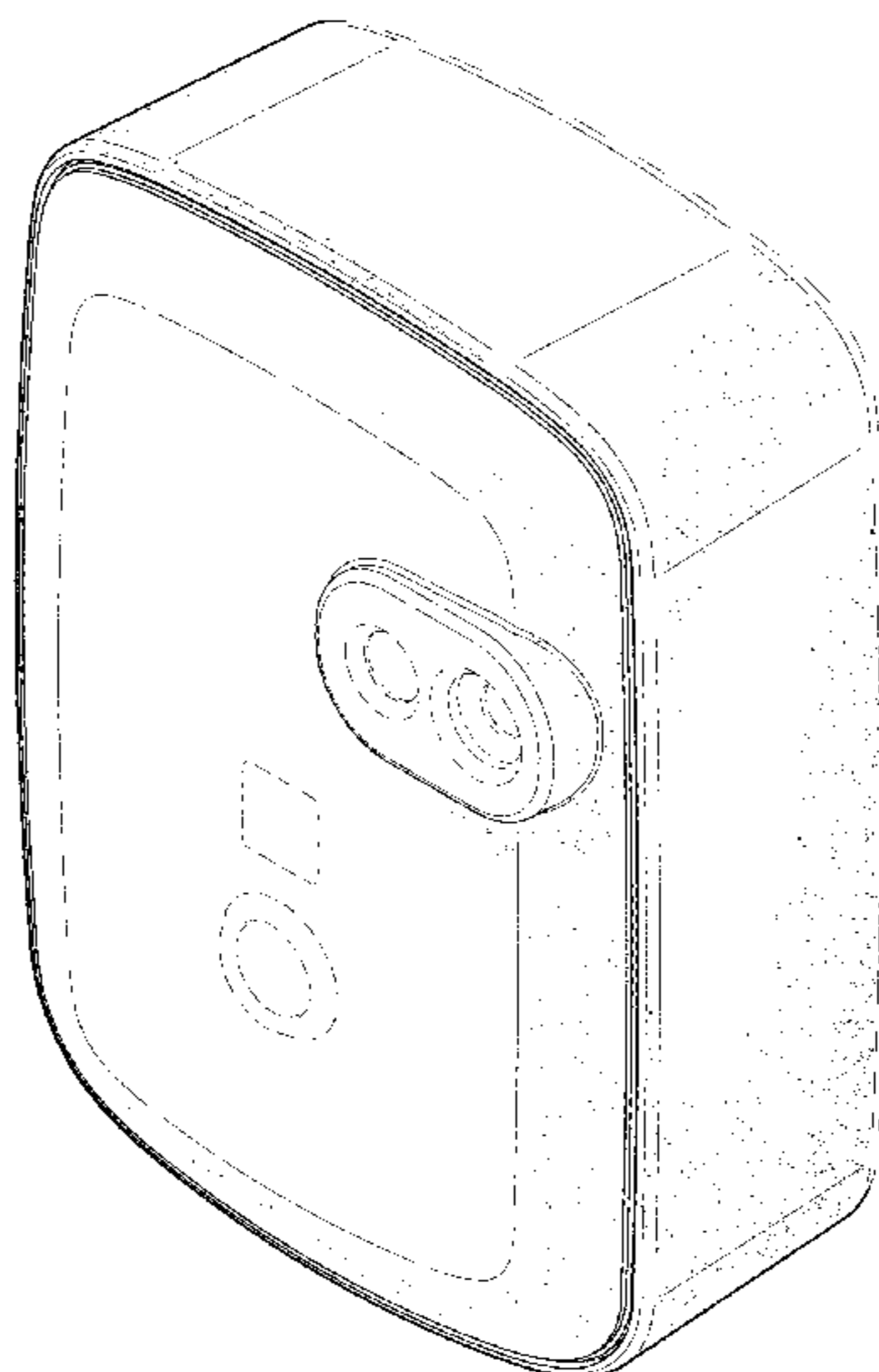
**DESCRIPTION**

FIG. 1 is a top front right perspective view of a thermal imaging sensor showing our new design.  
FIG. 2 is a bottom rear left perspective view thereof.  
FIG. 3 is a front elevation view thereof.  
FIG. 4 is a right side elevation view thereof.  
FIG. 5 is a left side elevation view thereof.  
FIG. 6 is a rear elevation view thereof.  
FIG. 7 is a top plan view thereof; and,  
FIG. 8 is a bottom plan view thereof.  
The broken lines in the figures show portions of the thermal imaging sensor that form no part of the claimed design. The dash-dot line defines the bounds of the claimed design and forms no part thereof. The stippling constitutes surface shading that merely clarifies contours of the surface of the claimed design and does not indicate surface texture, material, or color.

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**1 Claim, 7 Drawing Sheets**



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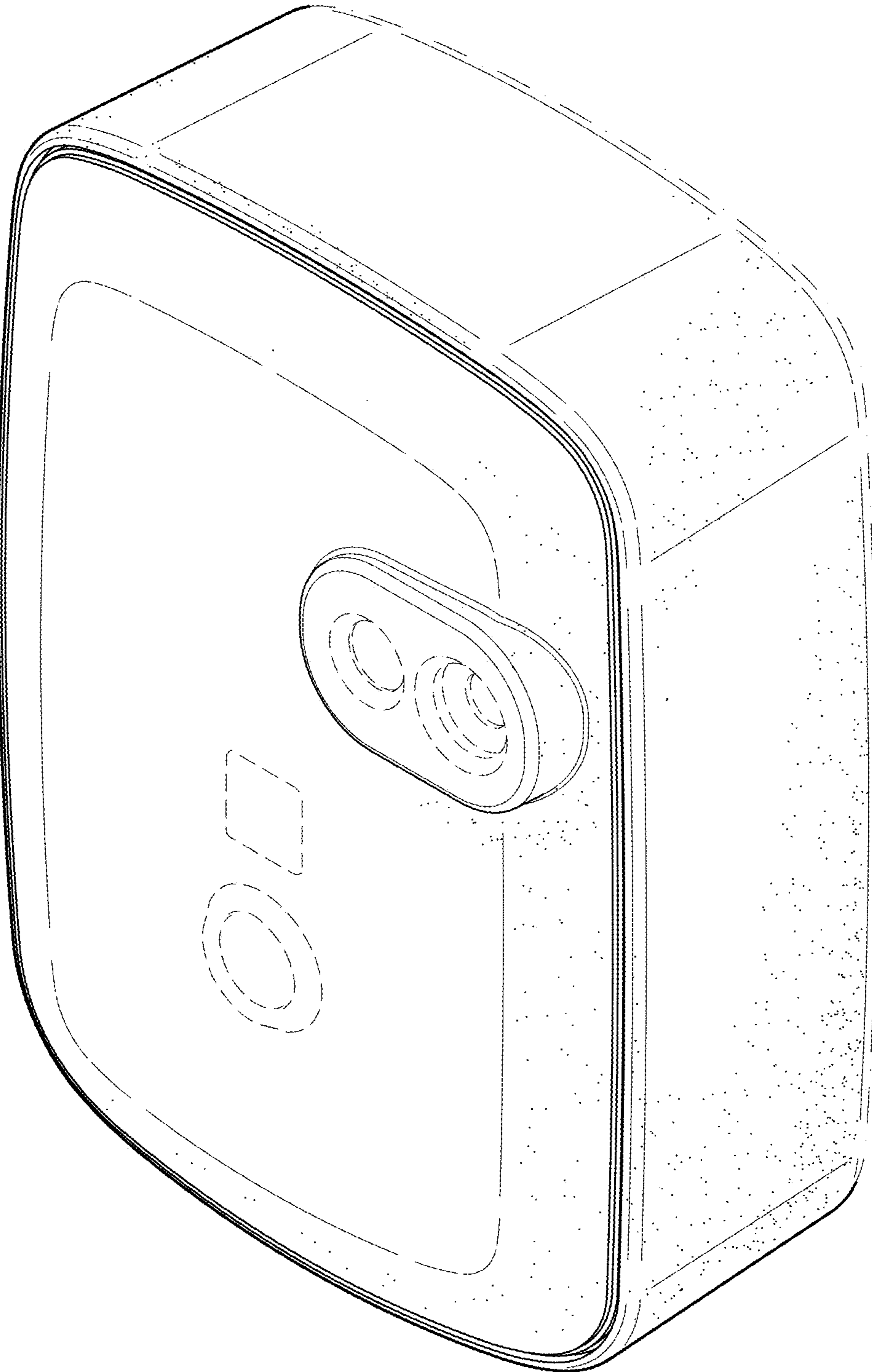


FIG. 1

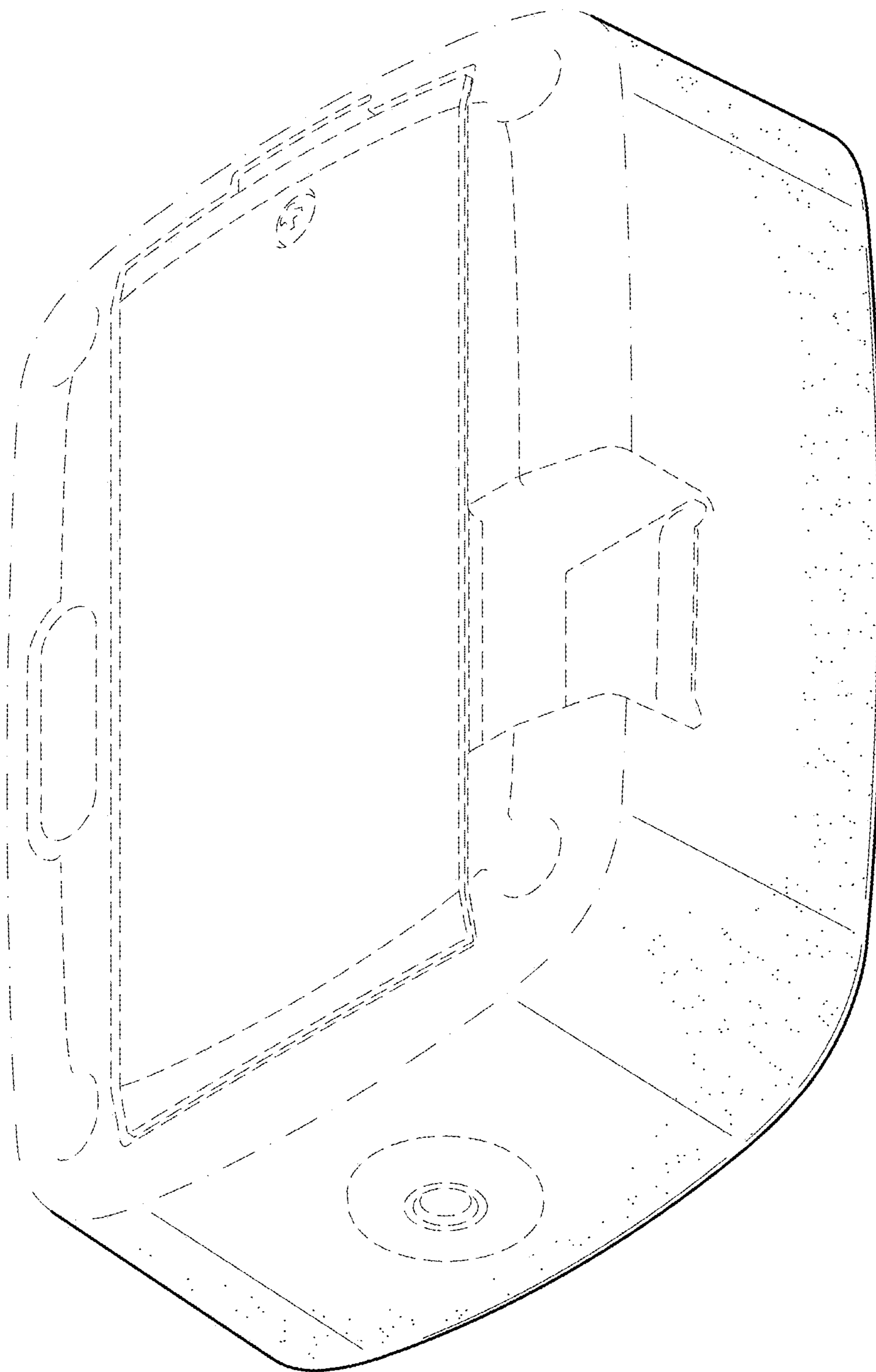


FIG. 2

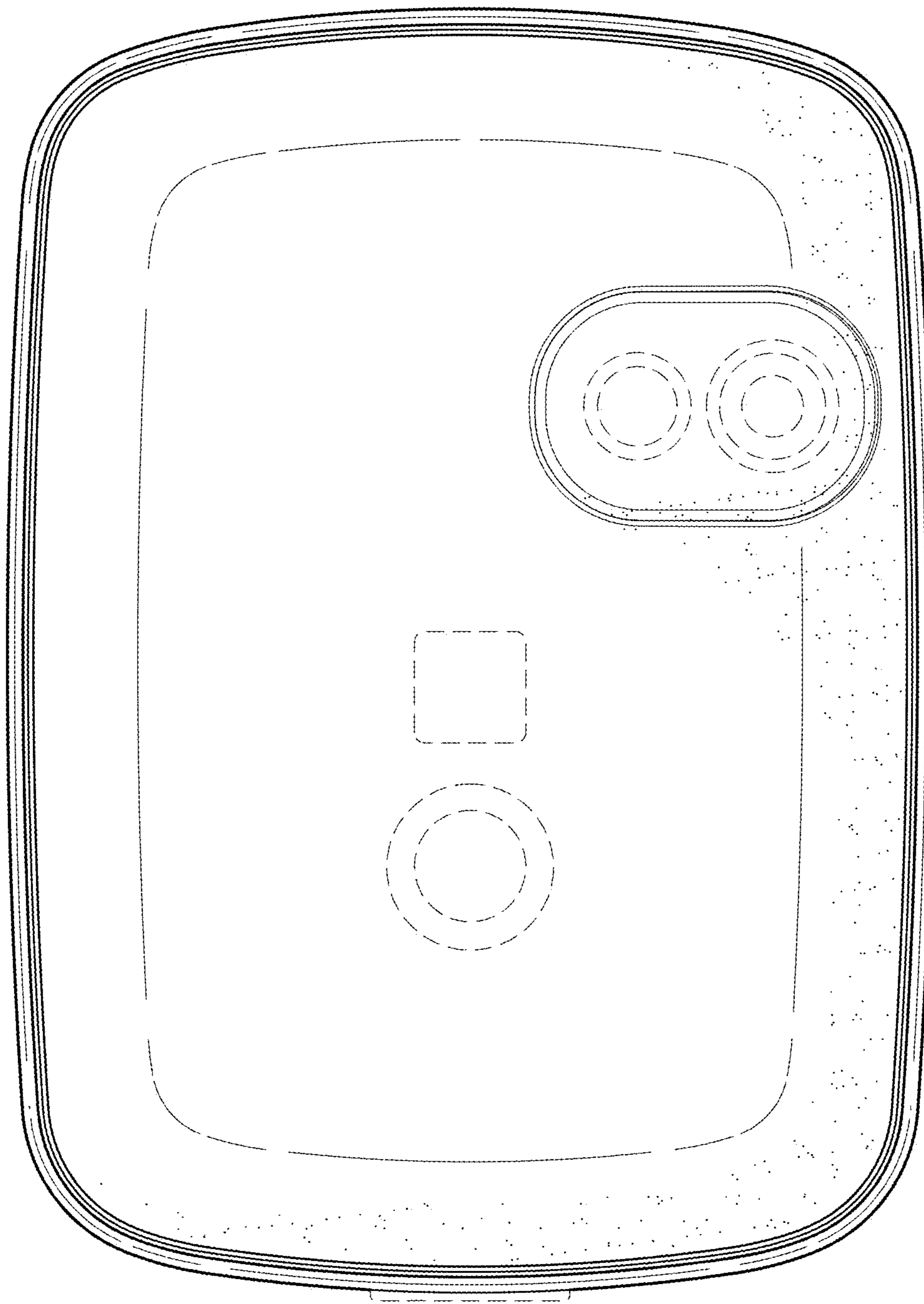


FIG. 3

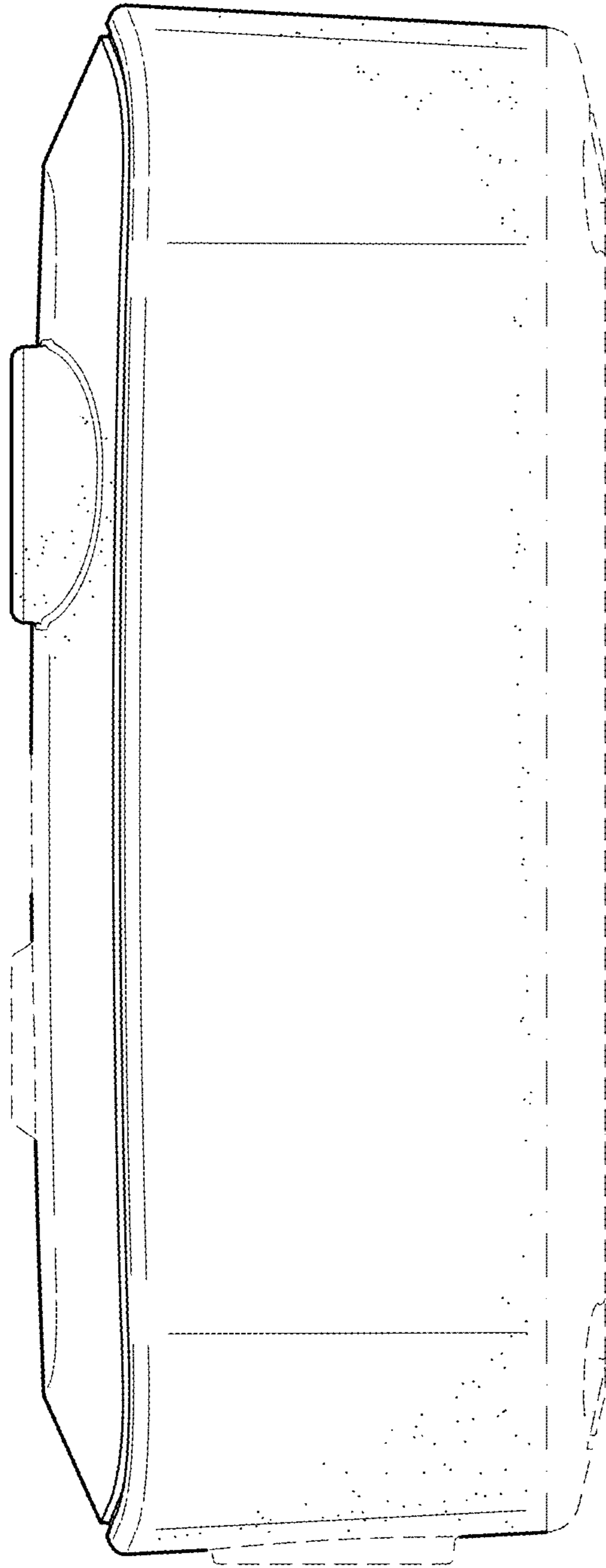


FIG. 4

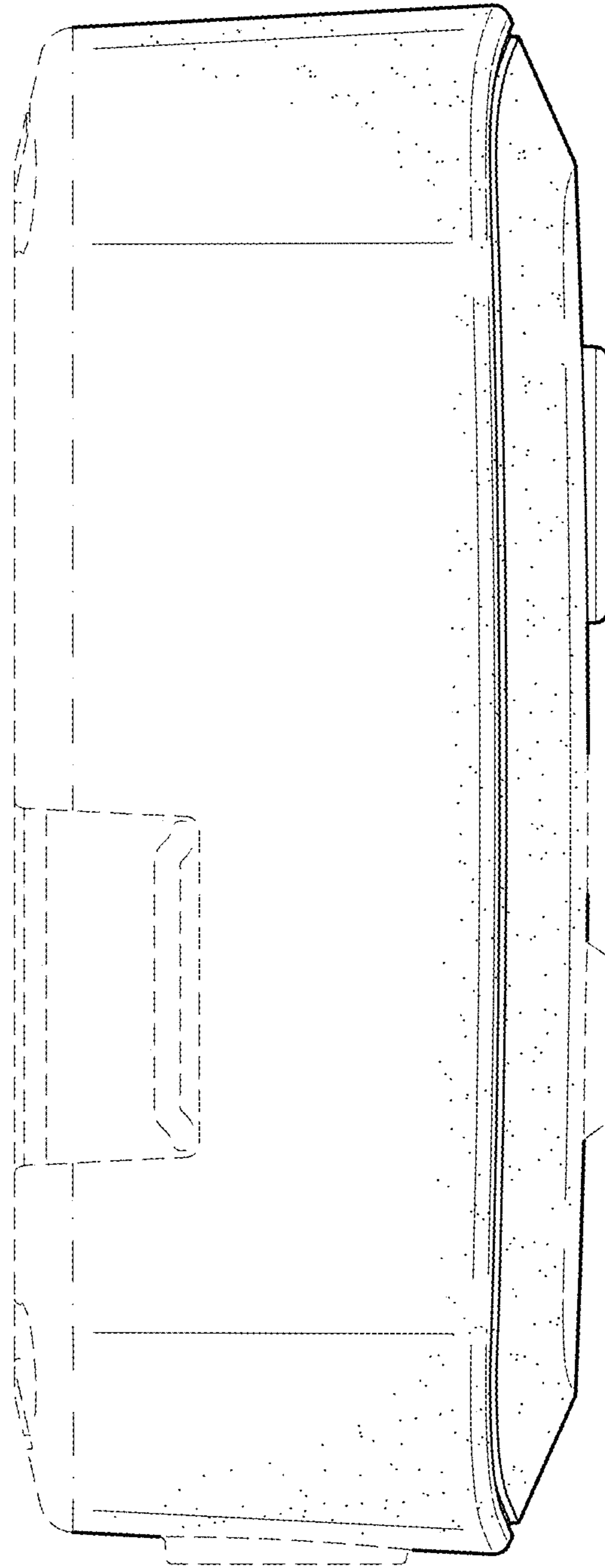


FIG. 5

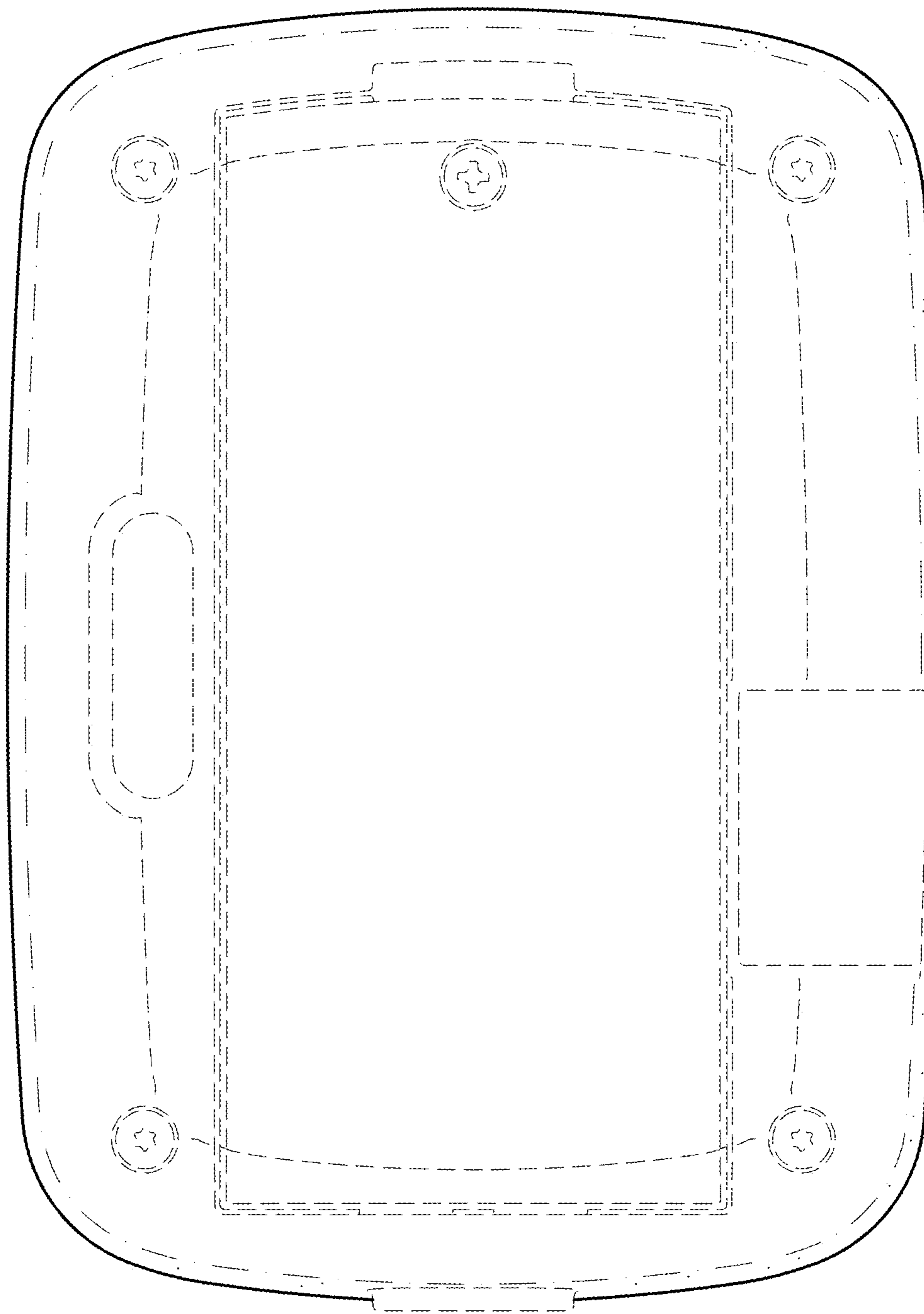


FIG. 6



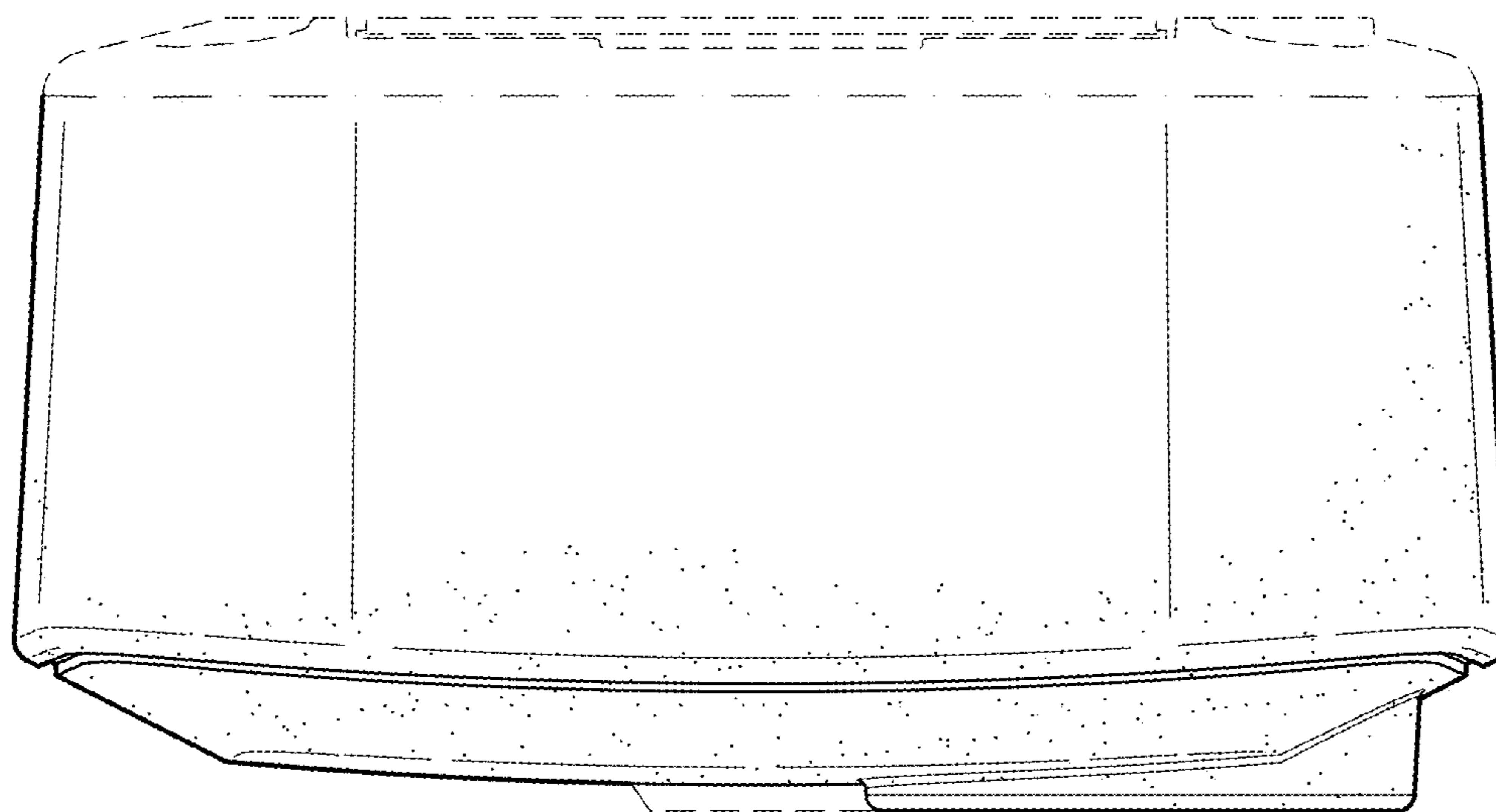


FIG. 7

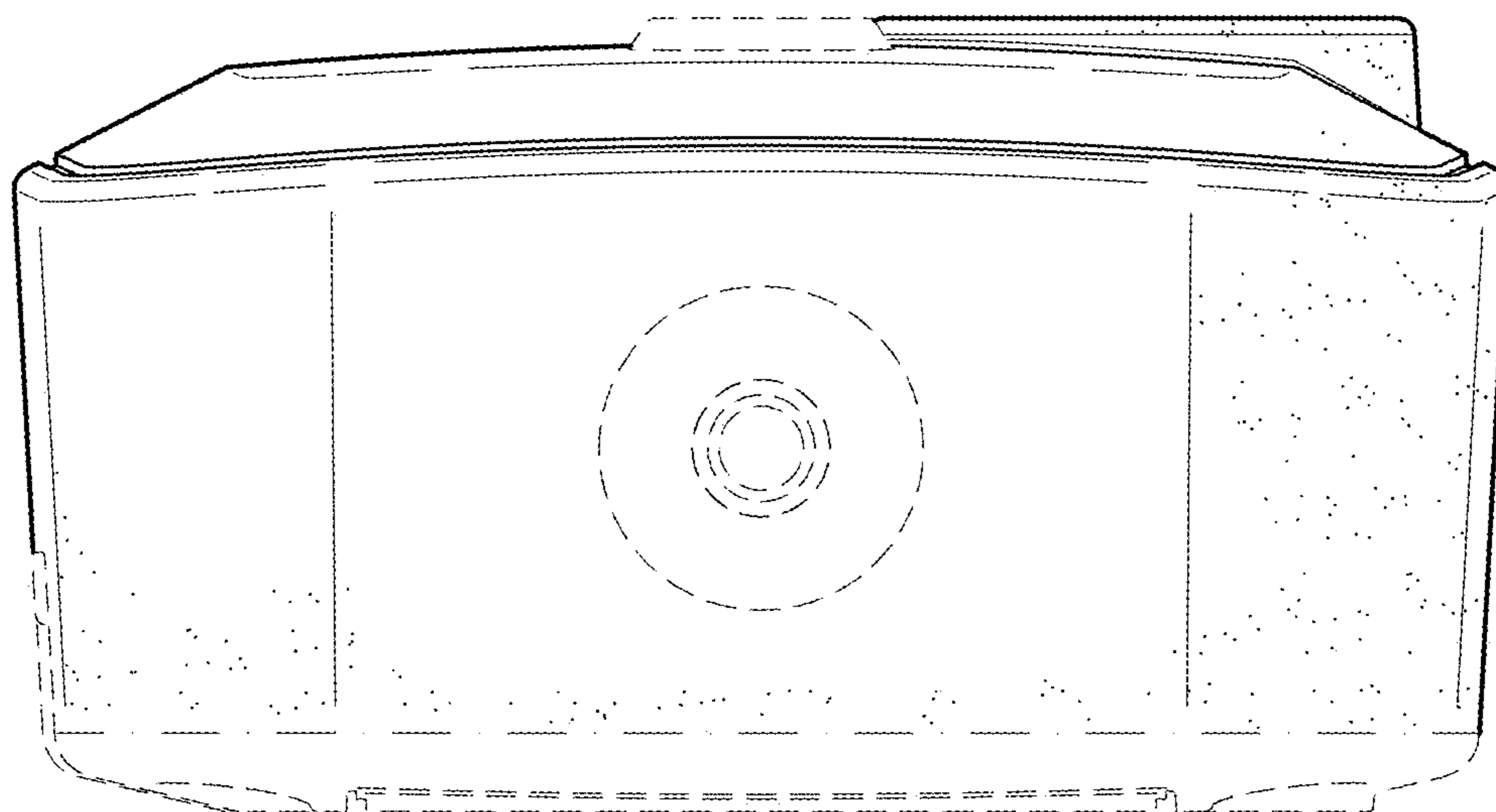


FIG. 8